

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	DONG WON SON	09/24/2020
	JONG HO SHIN	09/25/2020
	SUNG JAE LIM	09/25/2020
	SUNG HO CHOI	09/25/2020
	BYEONGHOON KIM	09/25/2020
	CHANGOH KIM	10/08/2020
	SUNGWON CHO	10/06/2020
	KYOUNGHEE PARK	10/07/2020
<b>RECEIVING PARTY DATA</b>		
<b>Name:</b>	STATS CHIPPAK PTE. LTD.	
<b>Street Address:</b>	5 YISHUN STREET 23	
<b>City:</b>	SINGAPORE	
<b>State/Country:</b>	SINGAPORE	
<b>Postal Code:</b>	768442	
<b>PROPERTY NUMBERS Total: 1</b>		
<b>Property Type</b>	<b>Number</b>	
<b>Application Number:</b>	17068482	
<b>CORRESPONDENCE DATA</b>		
<b>Fax Number:</b>		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
<b>Phone:</b>	480-499-9400	
<b>Email:</b>	main@plgaz.com	
<b>Correspondent Name:</b>	PATENT LAW GROUP: ATKINS AND ASSOCIATES	
<b>Address Line 1:</b>	123 W. CHANDLER HEIGHTS ROAD, #12535	
<b>Address Line 4:</b>	CHANDLER, ARIZONA 85248	
<b>ATTORNEY DOCKET NUMBER:</b>	2515.0524 CIP	
<b>NAME OF SUBMITTER:</b>	LISA ROSSETTI	
<b>SIGNATURE:</b>	/Lisa Rossetti/	

<b>DATE SIGNED:</b>	10/12/2020
<b>Total Attachments: 8</b> source=17068482ASSIGNMENT#page1.tif source=17068482ASSIGNMENT#page2.tif source=17068482ASSIGNMENT#page3.tif source=17068482ASSIGNMENT#page4.tif source=17068482ASSIGNMENT#page5.tif source=17068482ASSIGNMENT#page6.tif source=17068482ASSIGNMENT#page7.tif source=17068482ASSIGNMENT#page8.tif	

# ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, DONG WON SON of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).


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I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from any prior assignment, grant, mortgage, license, or other encumbrance.

28 Sep 2020  
Date Signed

  
Signature for DONG WON SON

## ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, JONG HO SHIN of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

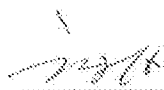
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9.25.2010  
Date Signed

  
Signature for JONG HO SHIN

# ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, SUNG JAE LIM of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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2020.9.25  
Date Signed

SJL  
Signature for SUNG JAE LIM

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For good and valuable consideration, the receipt of which is hereby acknowledged, I, SUNG HO CHOI of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).


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2020. 9. 25  
Date Signed

  
Signature for SUNG HO CHOI

## ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, BYEONGHOON KIM of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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2020. 09. 25  
Date Signed

  
Signature for BYEONGHOON KIM

# ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, CHANGOH KIM of Incheon, South Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled EMI SHIELDING FOR FLIP CHIP PACKAGE WITH EXPOSED DIE BACKSIDE, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0524 CIP, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

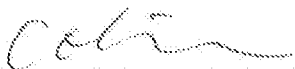
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20.10.08  
Date Signed

  
Signature for CHANGOH KIM



## ASSIGNMENT AND AGREEMENT

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2020.10.6

Date Signed



Signature for SUNGWON CHO

## ASSIGNMENT AND AGREEMENT

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2020.10.07  
Date Signed

  
Signature for KYOUNGHEE PARK